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Axis Communications
ARTPEC-4
Image Signal Processor

Basic Functional Analysis
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Image Signal Processor
Basic Functional Analysis

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FRAAR-1211-903
23656CYRF

Revision 1.0  Published: December 13, 2012
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Chipworks
1891 Robertson Road, Suite 500
Ottawa, Ontario  K2H 5B7
Canada
T  1-613-829-0414
F  1-613-829-0515
Web site: www.chipworks.com
Email: info@chipworks.com

Please send any feedback to feedback@chipworks.com